Brandner
Electronics

Maximum thickness

Maximum thickness, i.e. the final thickness is the thickness of a printed circuit board formed by summing up the material thickness and the thickness of the copper layer added during galvanisation.

The thickness of the solder mask is not included in the final thickness of the board. In the case of double-sided boards made of so-called regular materials (rigid), the thickness of the material is shown together with the thickness of the copper foil. In the case of multilayer boards, the thickness of the inner layer is shown without the copper foil!

For example: if the inner layer is 0.71 mm and the copper foil is 18/18 µ, the total thickness of the inner layer is 0.71+0.018+0.018=0.746 mm.

If a regular material is 1.6 mm and the copper foil is 18/18, 35/35, 70/70 or 105/105, the total thickness is still 1.6 mm! For all thicknesses, a tolerance of +/- 10% is used.

At Brandner Electronics, the maximum thickness is limited by the heights of conveyor rolls in chemical process lines.